

L Number	Hits	Search Text	DB	Time stamp
19	24	5689091.URPN.	USPAT	2002/10/23 08:57
20	5	("4170819"   "4211603"   "5319159"   "5487218"   "5557503").PN.	USPAT	2002/10/23 08:59
33	23	5600541.URPN.	USPAT	2002/10/23 09:00
34	12	("4630172"   "4705917"   "4899118"   "5012386"   "5043794"   "5121293"   "5128831"   "5164699"   "5239448"   "5247423"   "5319521"   "5412538").PN.	USPAT	2002/10/23 09:00
35	103	4630172.URPN.	USPAT	2002/10/23 09:02
38	37	5646828.URPN.	USPAT	2002/10/23 09:04
39	11	5963429.URPN.	USPAT	2002/10/23 09:05
40	0	6404648.URPN.	USPAT	2002/10/23 09:06
41	7	("5963429"   "6077724"   "6100594"   "6184463"   "6258626"   "6294838"   "6294839").PN.	USPAT	2002/10/23 09:06
42	18	("5088190"   "5528222"   "5541525"   "5566441"   "5600175"   "5607818"   "5633122"   "5634267"   "5656551"   "5682143"   "5733800"   "5767564"   "5784260"   "5811879"   "5818698"   "5875100"   "5898217"   "5963429").PN.	USPAT	2002/10/23 09:07
43	23	("3745505"   "3777221"   "4577214"   "4862323"   "5019673"   "5081563"   "5134246"   "5196089"   "5258575"   "5371404"   "5438224"   "5461197"   "5488542"   "5545924"   "5589781"   "5635761"   "5663593"   "5811879"   "5815372"   "5854534"   "5925934"   "5940687"   "6087732").PN.	USPAT	2002/10/23 09:08
44	13	5159750.URPN.	USPAT	2002/10/23 09:12
45	7	("4362902"   "4711700"   "4717066"   "4857483"   "5014111"   "5159750"   "5160409").PN.	USPAT	2002/10/23 09:13
46	24	("3676748"   "3890636"   "3892583"   "4079511"   "4115837"   "4132856"   "4286456"   "4320438"   "4340902"   "4396971"   "4475007"   "4513355"   "4551746"   "4630172"   "4654694"   "4677526"   "4705917"   "4801765"   "4839717"   "4866504"   "4872260"   "4879588"   "4890155"   "4891687").PN.	USPAT	2002/10/23 09:13
47	22	4879588.URPN.	USPAT	2002/10/23 09:14
48	4	5611876.URPN.	USPAT	2002/10/23 09:14
49	11	("3760090"   "4608592"   "4705917"   "4710250"   "4764846"   "4837408"   "4879588"   "4972253"   "5218230"   "5225709"   "5461196").PN.	USPAT	2002/10/23 09:15
50	6	5461196.URPN.	USPAT	2002/10/23 09:16
51	11	("3872583"   "4289922"   "4296456"   "4320438"   "4336088"   "4338621"   "4340902"   "4387388"   "4437141"   "4441119"   "4458291").PN.	USPAT	2002/10/23 09:21
54	19	5497031.URPN.	USPAT	2002/10/23 09:24
57	14	5357056.URPN.	USPAT	2002/10/23 09:25
58	4	5952714.URPN.	USPAT	2002/10/23 09:25

59	3	("5327325"   "5357056"   "5753857").PN.	USPAT	2002/10/23
64	17	4187868.URPN.	USPAT	09:25
65	6	("2874316"   "3050422"   "3499792"	USPAT	2002/10/23
110	24	"3527607"   "3871395"   "3998653").PN.	USPAT	09:27
		"5814883"	USPAT;	2002/10/23
			US-PGPUB;	09:27
			EPO; JPO;	2002/10/23
			DERWENT	09:37
111	76	"5583378"	USPAT;	2002/10/23
			US-PGPUB;	09:37
			EPO; JPO;	
			DERWENT	
112	29	"5796170"	USPAT;	2002/10/23
			US-PGPUB;	09:37
			EPO; JPO;	
			DERWENT	
113	20	"5491362"	USPAT;	2002/10/23
			US-PGPUB;	09:38
			EPO; JPO;	
			DERWENT	
114	22	"5444296"	USPAT;	2002/10/23
			US-PGPUB;	09:38
			EPO; JPO;	
			DERWENT	
115	155	"5814883" "5583378" "5796170" "5491362"	USPAT;	2002/10/23
		"5444296"	US-PGPUB;	09:38
			EPO; JPO;	
			DERWENT	
116	38	(US-6407381-\$ or US-6384473-\$ or	USPAT;	2002/10/23
		US-6271056-\$ or US-5952714-\$ or	US-PGPUB	09:38
		US-5753857-\$ or US-5107328-\$ or		
		US-6451624-\$ or US-5689091-\$ or		
		US-5633530-\$ or US-6440770-\$ or		
		US-6043559-\$ or US-6324067-\$ or		
		US-5043794-\$ or US-5600541-\$ or		
		US-5497031-\$ or US-5357056-\$ or		
		US-4187868-\$ or US-5327325-\$ or		
		US-6420782-\$ or US-5012386-\$ or		
		US-4630172-\$ or US-5672909-\$ or		
		US-5173767-\$ or US-6117193-\$ or		
		US-6396116-\$ or US-6342670-\$).did. or		
		(US-6214644-\$ or US-5963429-\$ or		
		US-6445591-\$ or US-6404648-\$ or		
		US-6294839-\$ or US-6184463-\$ or		
		US-6380631-\$ or US-4879588-\$ or		
		US-5461196-\$ or US-5611876-\$ or		
		US-4513355-\$).did. or		
		(US-20020006687-\$).did.		
117	151	("5814883" "5583378" "5796170" "5491362"	USPAT;	2002/10/23
		"5444296") not ((US-6407381-\$ or	US-PGPUB;	09:38
		US-6384473-\$ or US-6271056-\$ or	EPO; JPO;	
		US-5952714-\$ or US-5753857-\$ or	DERWENT	
		US-5107328-\$ or US-6451624-\$ or		
		US-5689091-\$ or US-5633530-\$ or		
		US-6440770-\$ or US-6043559-\$ or		
		US-6324067-\$ or US-5043794-\$ or		
		US-5600541-\$ or US-5497031-\$ or		
		US-5357056-\$ or US-4187868-\$ or		
		US-5327325-\$ or US-6420782-\$ or		
		US-5012386-\$ or US-4630172-\$ or		
		US-5672909-\$ or US-5173767-\$ or		
		US-6117193-\$ or US-6396116-\$ or		
		US-6342670-\$).did. or (US-6214644-\$ or		
		US-5963429-\$ or US-6445591-\$ or		
		US-6404648-\$ or US-6294839-\$ or		
		US-6184463-\$ or US-6380631-\$ or		
		US-4879588-\$ or US-5461196-\$ or		
		US-5611876-\$ or US-4513355-\$).did. or		
		(US-20020006687-\$).did.)		

118	17	("5444296"   "5652463"   "5674785"   "5808878"   "5952611"   "5956233"   "5973403"   "5994166"   "6013948"   "6020629"   "6091138"   "6181002"   "6181008"   "6219254"   "6262488"   "6265771"   "6316727"   "2001/0015485").PN.	USPAT	2002/10/23 09:39
119	20	5444296.URPN.	USPAT	2002/10/23 09:40
120	2	("5172303"   "5239448").PN.	USPAT	2002/10/23 09:40
121	11	("4675789"   "5557502"   "5583378"   "5625166"   "5640048"   "5796170"   "5814883"   "5831810"   "5847936"   "5923540"   "6153829").PN.	USPAT	2002/10/23 09:44
122	8	5923540.URPN.	USPAT	2002/10/23 09:45
123	4	5831810.URPN.	USPAT	2002/10/23 09:46
124	5	("5081563"   "5103283"   "5210683"   "5272590"   "5403784").PN.	USPAT	2002/10/23 09:47
125	26	5796170.URPN.	USPAT	2002/10/23 09:50
126	2	("4954877"   "5371404").PN.	USPAT	2002/10/23 09:50
127	29	("3926746"   "4681656"   "4792646"   "4802277"   "4849856"   "4910584"   "4970579"   "4999740"   "5027191"   "5045921"   "5057969"   "5115964"   "5133495"   "5136366"   "5153385"   "5159535"   "5170931"   "5191511"   "5203075"   "5241133"   "5261155"   "5280193"   "5291062"   "5294750"   "5332864"   "5345106"   "5357672"   "5381039"   "5420460").PN.	USPAT	2002/10/23 09:51
128	6	("5222014"   "5237204"   "5444296"   "5543663"   "5567983"   "5633783").PN.	USPAT	2002/10/23 09:59
129	19944	((optical near1 (device package)) and (window transparent))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:06
130	683	((optical near1 (device package)) and (window transparent)) and (second adj (chip die device semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:10
131	20486	((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:09
132	699	((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:20
133	359	((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:13
134	215	((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:21
135	148	((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:20

136	147	(((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity apperture opening)) not ((US-6407381-\$ or US-6384473-\$ or US-6271056-\$ or US-5952714-\$ or US-5753857-\$ or US-5107328-\$ or US-6451624-\$ or US-5689091-\$ or US-5633530-\$ or US-6440770-\$ or US-6043559-\$ or US-6324067-\$ or US-5043794-\$ or US-5600541-\$ or US-5497031-\$ or US-5357056-\$ or US-4187868-\$ or US-5327325-\$ or US-6420782-\$ or US-5012386-\$ or US-4630172-\$ or US-5672909-\$ or US-5173767-\$ or US-6117193-\$ or US-6396116-\$ or US-6342670-\$).did. or (US-6214644-\$ or US-5963429-\$ or US-6445591-\$ or US-6404648-\$ or US-6294839-\$ or US-6184463-\$ or US-6380631-\$ or US-4879588-\$ or US-5461196-\$ or US-5611876-\$ or US-4513355-\$).did. or (US-20020006687-\$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:15
137	551	((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) not ((((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity apperture opening))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:20
138	131	(((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) not ((((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity apperture opening))) and (cavity apperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:20
139	238	(((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) not ((((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity apperture opening))) and (cavity aperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:20
140	161	(((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:21

141	13	(((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening)) not ((((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:21
142	161	(((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening)) ((((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening)) ((((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening)) not ((((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:21
143	68	(((((optical near1 (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening)) and (bump ball flipchip (flip adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 10:22

144	7	(((((((optical nearl (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening)) and (bump ball flipchip (flip adj chip))) not (((((((optical nearl (device package)) (ccd adj chip)) and (window (glass adj cover) transparent)) and (second adj (chip die device semiconductor))) and glass) and (wiring wire bump ball flipchip (flip adj chip))) and (cavity aperture opening)) not ((US-6407381-\$ or US-6384473-\$ or US-6271056-\$ or US-5952714-\$ or US-5753857-\$ or US-5107328-\$ or US-6451624-\$ or US-5689091-\$ or US-5633530-\$ or US-6440770-\$ or US-6043559-\$ or US-6324067-\$ or US-5043794-\$ or US-5600541-\$ or US-5497031-\$ or US-5357056-\$ or US-4187868-\$ or US-5327325-\$ or US-6420782-\$ or US-5012386-\$ or US-4630172-\$ or US-5672909-\$ or US-5173767-\$ or US-6117193-\$ or US-6396116-\$ or US-6342670-\$).did. or (US-6214644-\$ or US-5963429-\$ or US-6445591-\$ or US-6404648-\$ or US-6294839-\$ or US-6184463-\$ or US-6380631-\$ or US-4879588-\$ or US-5461196-\$ or US-5611876-\$ or US-4513355-\$).did. or (US-20020006687-\$).did.))	USPAT; US-PGPUB; EPO; JPO; DERWENT.	2002/10/23 10:22
-----	---	---	--	---------------------

L Number	Hits	Search Text	DB	Time stamp
1	378	((high low) adj temperature adj cofired adj ceramic)((high low) adj temperature adj "co-fired" adj ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 14:25
2	164	((high low) adj temperature adj cofired adj ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 14:26
3	112	((high low) adj temperature adj cofired adj ceramic)((high low) adj temperature adj "co-fired" adj ceramic)) and (light optic optical image ((ccd led mems imems vcSEL) adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/23 14:33
4	5	("3654947"   "5640995"   "5964239"   "6102068"   "6136212").PN.	USPAT	2002/10/23 14:37
5	5	("5948533"   "6031729"   "6090468"   "6145380"   "6228467").PN.	USPAT	2002/10/23 14:39
6	3	6011294.URPN.	USPAT	2002/10/23 14:48